



Product Change Notification

112414 - 00

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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

Americas Contact: asmo.pcn@intel.com

Asia Pacific/PRC Contact: apacgccb@intel.com

Europe Email: eccb@intel.com

Japan Email: jccb.ijkk@intel.com

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Product Change Notification

Change Notification #: 112414 - 00
Change Title: Intel® Computer Module HNS2600WP and HNS2600WPQ
PCN 112414-00, Product Design
BMC Chip Update
Date of Publication: July 2, 2013

Key Characteristics of the Change:

Product Design

Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material *:	Jul 31, 2013
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** Intel appreciates the customer's desire to receive the latest revision of products. However, Intel manages inventory on a first in first out (FIFO) basis at the MM# level. Subsequently, customer requests for a specific revision of material (below the MM#) will not be supported by Intel.*

Description of Change to the Customer:

Intel is implementing the following changes to Intel® Computer Module HNS2600WP and HNS2600WPQ:

1. Integrated BMC chip update to revision P02; the previous revision P01 is end of life.
2. Changed the shape of the insulator on the air duct to make installation easier.

Customer Impact of Change and Recommended Action:

Intel anticipates no impact to customers. Customers may need to validate the function and feature changes after receiving the systems.

Products Affected / Intel Ordering Codes:

Product Code	MM#	Pre Change TA	Pre Change PBA	Post Change TA	Post Change PBA
HNS2600WPQ	918377	G54630-001	G17128-203	G54630-002	G17128-204
HNS2600WP	918378	G54633-001	G38670-204	G54633-002	G38670-205

PCN Revision History:

Date of Revision: July 2, 2013	Revision Number: 00	Reason: Originally Published PCN
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